Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
			* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-05-07
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Flavio Di Francesco	Representative Title	AMS Materials Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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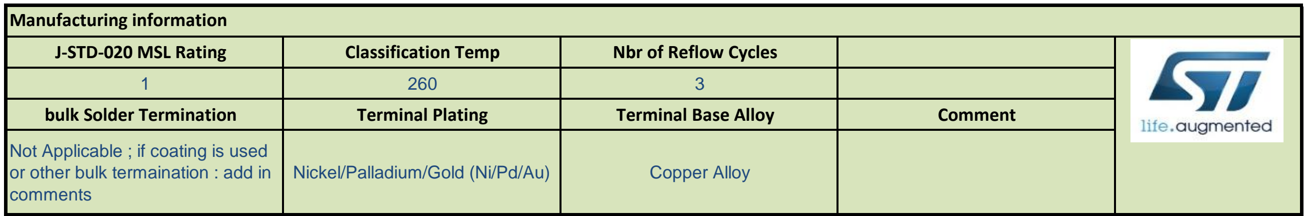
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HYWY*Z121AFJ	A	ZS1A	2015-05-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	16.38	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termaination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.9- 1.6-1.05	5	gull wing	
Comment	Package: SOT 23-5; MD valid for TSZ121ILT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList :REACH-17th December 2014				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HYWY*Z121AFJ						
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Silicon Die	Other inorganic materials	0.423	mg	supplier	die	Silicon (Si)	7440-21-3		0.405	mg	957447	24733
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	9456	244
Silicon Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	2364	61
Silicon Die				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	2364	61
Silicon Die				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	16548	427
Silicon Die				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.005	mg	11820	305
Lead-frame	Copper & its alloys	7.2	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.936	mg	963333	423573
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.162	mg	22500	9893
Lead-frame				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	278	122
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.009	mg	1250	550
Lead-frame				supplier	metallization	Nickel (Ni)	7440-02-0		0.083	mg	11528	5069
Lead-frame				supplier	metallization	Palladium (Pd)	7440-05-3		0.007	mg	972	427
Lead-frame				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	139	61
Die Attach	Other Organic Material	0.07	mg	Supplier	Glue	Epoxyde Bisphenol A Resin	25068-38-6		0.02	mg	285714	1221
Die Attach				Supplier	Glue	Aromatic amine	Proprietary		0.003	mg	42857	183
Die Attach				Supplier	Glue	Glycol ether ester	Proprietary		0.003	mg	42857	183
Die Attach				Supplier	Glue	silica	60676-86-0		0.021	mg	300000	1282
Die Attach				Supplier	Glue	Aluminium oxide	1344-28-1		0.023	mg	328571	1405
Bonding Wire	Precious metals	0.15	mg	Supplier	Bonding Wire	Gold (Au)	7440-57-5		0.15	mg	1000000	9160
encapsulation	Other Inorganic Material	8.537	mg	supplier	mold compound	Silica, vitreous	60676-86-0		7.396	mg	866346	451664
encapsulation				supplier	mold compound	phenolic resin	Proprietary		0.272	mg	31861	16611
encapsulation				supplier	mold compound	epoxy resin	Proprietary		0.31	mg	36313	18931
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.155	mg	18156	9466
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.016	mg	1874	977
encapsulation				supplier	mold compound	Zinc hydroxide	20427-58-1		0.078	mg	9137	4763
encapsulation				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.31	mg	36313	18931